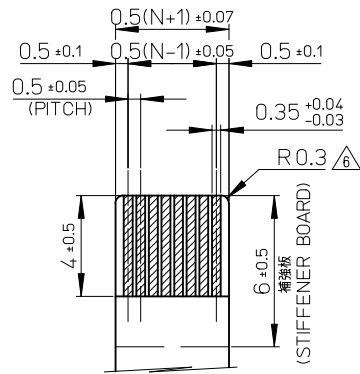


16.1	14.3	10.65	9.5	52745-2097	20
15.6	13.8	10.15	9	52745-1997	19
15.1	13.3	9.65	8.5	52745-1897	18
14.6	12.8	9.15	8	52745-1797	17
14.1	12.3	8.65	7.5	52745-1697	16
13.6	11.8	8.15	7	52745-1597	15
13.1	11.3	7.65	6.5	52745-1497	14
12.6	10.8	7.15	6	52745-1397	13
12.1	10.3	6.65	5.5	52745-1297	12
11.6	9.8	6.15	5	52745-1197	11
11.1	9.3	5.65	4.5	52745-1097	10
10.6	8.8	5.15	4	52745-0997	9
10.1	8.3	4.65	3.5	52745-0897	8
9.6	7.8	4.15	3	52745-0797	7
9.1	7.3	3.65	2.5	52745-0697	6
8.1	6.3	2.65	1.5	52745-0497	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

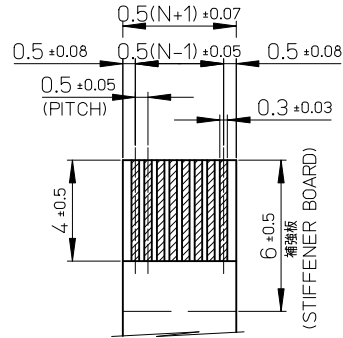
CONNECTOR SERIES NO. : 52745-\*\*59

REVISED EC NO. J2011-0041 DRWN:HYOSHINO 2010/07/08 CHK'D:SHIMIZUYAMA 2010/07/08 APPR:KMORIKAWA 2010/07/16	DESCRIPTION 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		DRAWN BY M. NABE I	DATE '05/02/14	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) GOLD PLATING			
		CHECKED BY K. TOJO	DATE '05/02/14	MOLEX INCORPORATED			
		APPROVED BY N. UKITA	DATE '05/02/14	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-52745-050	SHEET NO. 1 OF 2	

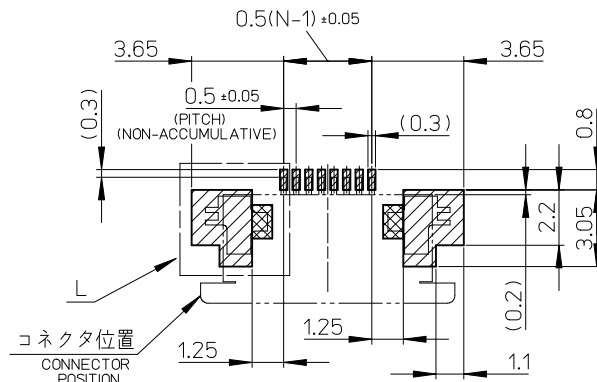
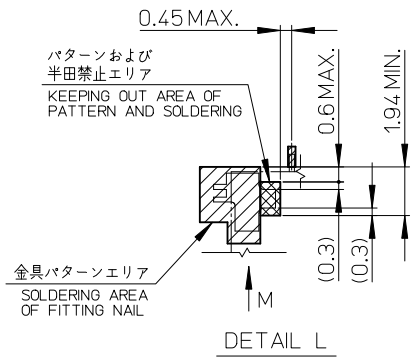
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



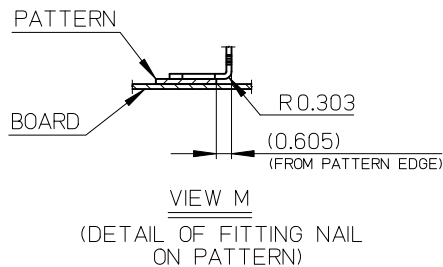
適合金めっきFPC推奨寸法  
 APPLICABLE FPC OF GOLD  
 PLATING RECOMMENDED DIMENSION  
 仕上がり厚さ: 0.3±0.03  
 THICKNESS: 0.3±0.03/-0.03



適合金めっきFFC推奨寸法  
 APPLICABLE FFC OF GOLD  
 PLATING RECOMMENDED DIMENSION  
 仕上がり厚さ: 0.3±0.03  
 THICKNESS: 0.3±0.03/-0.03



参考基板レイアウト  
 (マウント面)  
 RECOMMENDED P.C BOARD  
 PATTERN DIMENSION(REF.)  
 (MOUNTING SIDE)



注記NOTES

1.使用材料

MATERIAL

ハウジング: 46ナイロン、ガラス充填、UL94V-0、白  
 HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE  
 アクチュエータ: ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、黒  
 ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK  
 ターミナル: リン青銅、ニッケル下地金めっき (t=0.2)  
 TERMINAL: PHOSPHOR BRONZE, GOLD OVER NICKEL PLATING  
 金具: リン青銅、ニッケル下地金めっき (t=0.2)  
 FITTING NAIL: PHOSPHOR BRONZE, TIN OVER NICKEL PLATING

2.エンボステープ梱包時は、アクチュエータがロックした状態になります。

IN THE PACKAGE, ACTUATOR OF PART NO.52745-\*\*59 SHOULD BE LOCKED.

3. ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。  
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM DATUM-H.  
 UPPER DIRECTION: 0.1MAXIMUM  
 LOWER DIRECTION: 0.15 MAXIMUM

4. 偶数極に適用

APPLY FOR EVEN CIRCUIT.

5. ハ・ターン剥離止め金具

FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.

6. R0.3は、FPCの胴体部にかからないこと  
 R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

7.ELV 及び RoHS 適合品

ELV AND RoHS COMPLIANT

FPCについて:

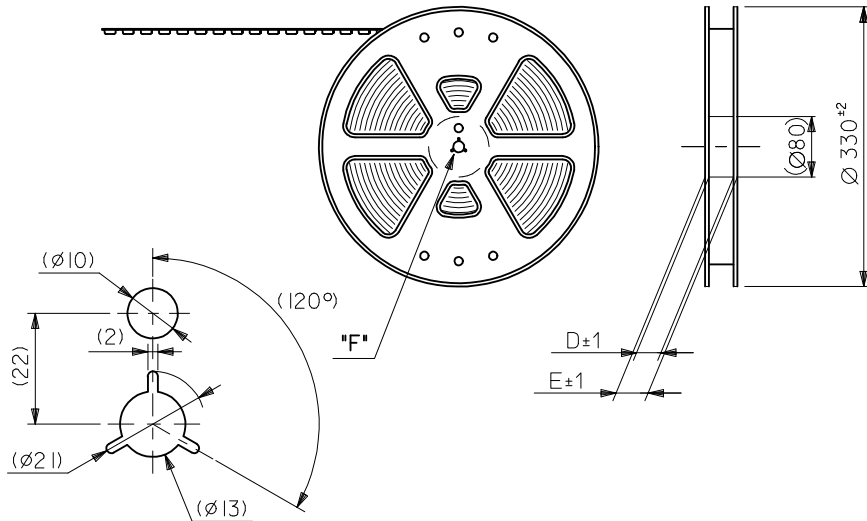
打抜き方向は導体側から補強板を推奨致します。  
 補強フィルム材質はポリイミドを推奨致します。  
 接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
 RECOMMENDED MATERIAL :  
 STIFFENER FILM : POLYIMIDE  
 BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2011-0041 DRWN:HYOSHINO 2010/07/08 CHKD:SHIMOMIYAMA 2010/07/08 APPR:KMORIKAWA 2010/07/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY M. NABE I	DATE '05/02/14	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) GOLD PLATING			
		10 OVER 30 UNDER	± ---	CHECKED BY K. TOJO	DATE '05/02/14	MOLEX INCORPORATED			
		30 OVER	± ---	APPROVED BY N. UKITA	DATE '05/02/14				
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-52745-050	SHEET NO. 2 OF 2			
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

引き出し方向  
←  
PULL OUT  
DIRECTION



**DETAIL "F"**

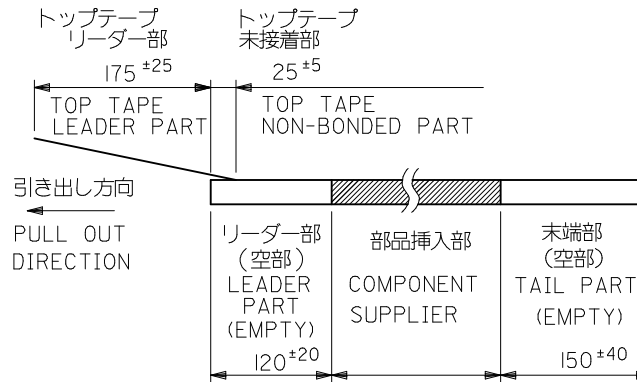
5. 材料 キャリアテープ:ポリプロピレン (PP)  
 トップテープ:PET, PE, PEF  
 リール:ポリスチレン (PS) <リサイクル材を含む>  
 MATERIAL CARRIER TAPE:POLYPROPYLENE  
 TOP TAPE:PET,PE,PEF  
 REEL:POLYSTYRENE(PS)  
 <RECYCLE MATERIAL CONTAINED>

6. 本製品は 52745- \*\*90 の鉛フリー品である。  
 THIS PRODUCT IS LEAD FREE OF 52745-\*\*90

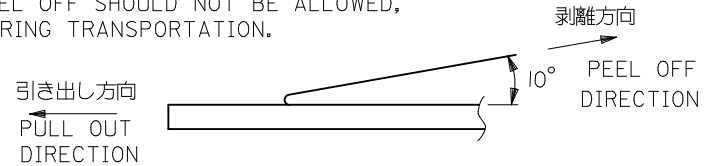
7. 本製品は乾燥剤入り、ハイバリア梱包仕様である。  
 THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

注記 NOTES

- 製品番号 52745-\*\*59 の梱包状態はアクチュエータがロックした状態とする。  
 詳細寸法については図面 SD-52745-050 を参照下さい。  
 IN THE PACKAGE,ACTUATOR OF PART NO.52745-\*\*59 SHOULD BE LOCKED  
 RE DETAILED DIMENSIONS,SEE SD-52745-050.
- 梱包数量:1000個/リール  
 NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

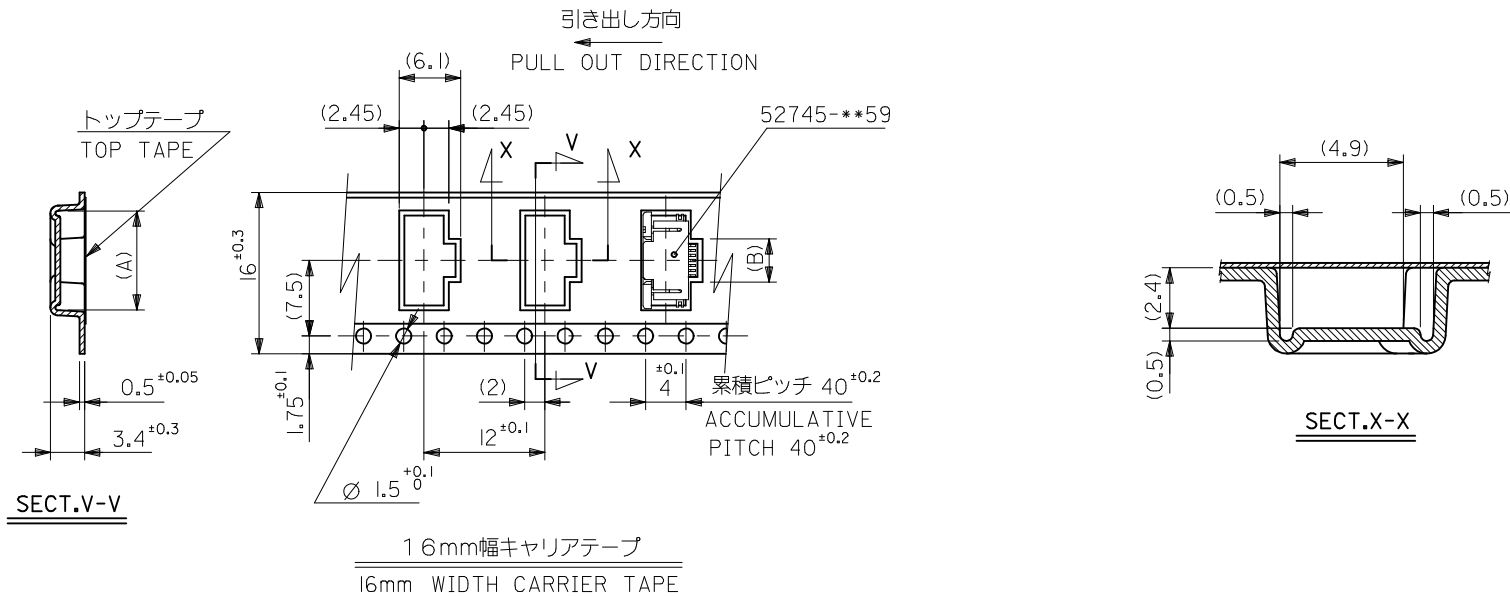


- トップテープの剥離強度:(剥離方向は下図参照)  
 0.1N~1.3N(10gf~130gf)尚、本規格値は、出荷時に適用。  
 (但し、輸送時に剥離が発生しない事。)  
 PEELING OFF FORCE OF TOP TAPE:  
 0.1N~1.3N(10gf~130gf)(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
 PEEL OFF SHOULD NOT BE ALLOWED,  
 DURING TRANSPORTATION.



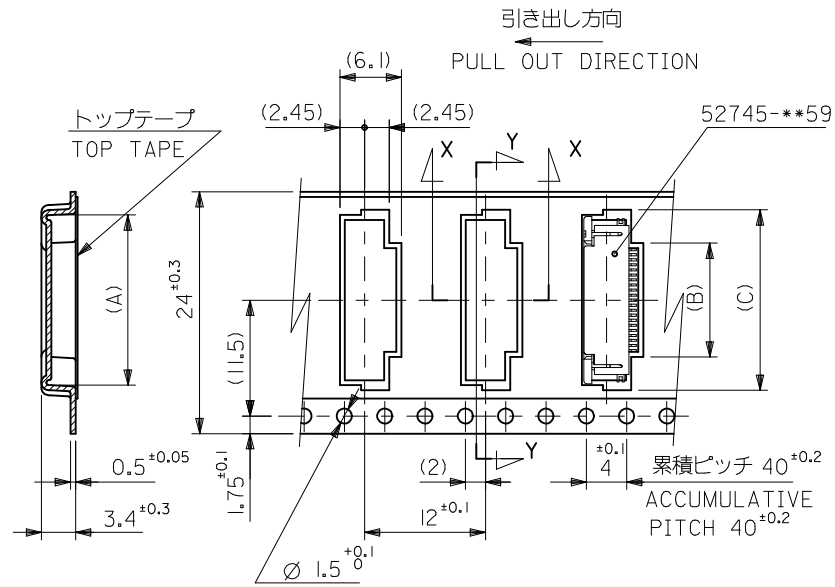
52745-\*\*97 MODEL NO.

REVISED EC NO: J2009-2061 DRWN:TKON 2009/05/20 CHKD:HMATSUMOTO 2009/05/21 APPR:NUKITA 2009/05/21	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±---	DRAWN BY M.NABEI	DATE '05/02/14	TITLE 0.5 FPC CONN UPR CONT EMBSTP PKG -LEAD FREE-			
		10 OVER 30 UNDER	±---	CHECKED BY K.TOJO	DATE '05/02/14	MOLEX INCORPORATED			
		30 OVER	±---	APPROVED BY N.UKITA	DATE '05/02/14	DOCUMENT NO. SD-52745-051			
ANGULAR ±---°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 3			
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



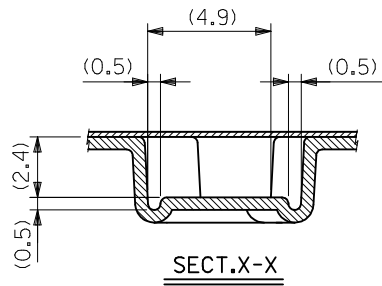
16	21.4	17.4	2.8	8.4	52745-0497	4
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO.: J2009-2061 DRWN:TKGN 2009/05/20 CHKD:HMATSUMOTO 2009/05/21 APPR:NUKITA 2009/05/21	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	REV	10 UNDER ±---	DRAWN BY M. NABEI	DATE '05/02/14	TITLE 0.5 FPC CONN UPR CONT EMBSTP PKG -LEAD FREE-	
		10 OVER 30 UNDER ±---	CHECKED BY K. TOJO	DATE '05/02/14	APPROVED BY N. UKITA	
		30 OVER ±---	DATE '05/02/14	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-52745-051
		ANGULAR ±--- °	MOLEX INCORPORATED			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



SECT.Y-Y

24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE



SECT.X-X

24	29.4	25.4	17.4	10.8	16.4	52745-2097	20
			16.9	10.3	15.9	-1997	19
			16.4	9.8	15.4	-1897	18
			15.9	9.3	14.9	-1797	17
			15.4	8.8	14.4	-1697	16
			14.9	8.3	13.9	-1597	15
			14.4	7.8	13.4	-1497	14
			13.9	7.3	12.9	-1397	13
			13.4	6.8	12.4	-1297	12
			12.9	6.3	11.9	-1197	11
			12.4	5.8	11.4	-1097	10
			11.9	5.3	10.9	-0997	9
			11.4	4.8	10.4	-0897	8
10.9	4.3	9.9	-0797	7			
10.4	3.8	9.4	52745-0697	6			
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2009-2061 DRWN:TKON 2009/05/20 CHKD:HMATSUMOTO 2009/05/21 APPR:NUKITA 2009/05/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±---	DRAWN BY M. NABEI	DATE '05/02/14	TITLE 0.5 FPC CONN UPR CONT EMBSTP PKG -LEAD FREE-		
	10 OVER 30 UNDER	±---	CHECKED BY K. TOJO	DATE '05/02/14	MOLEX INCORPORATED		
	30 OVER	±---	APPROVED BY N. UKITA	DATE '05/02/14	DOCUMENT NO. SD-52745-051	SHEET NO. 3 OF 3	
	ANGULAR ±--- °		MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
REVISION A	DESCRIPTION DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						